

30V N+P-Channel Enhancement Mode MOSFET

Description

The AP40G03NF uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 30V$ $I_D = 42A$

$R_{DS(ON)} < 10m\Omega$ @ $V_{GS}=10V$ (Type: **6.5m Ω**)

$V_{DS} = -30V$ $I_D = -38A$

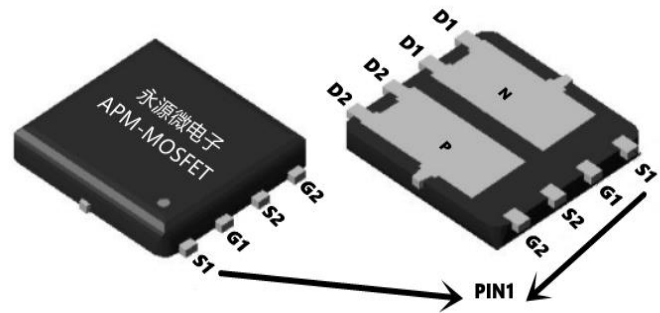
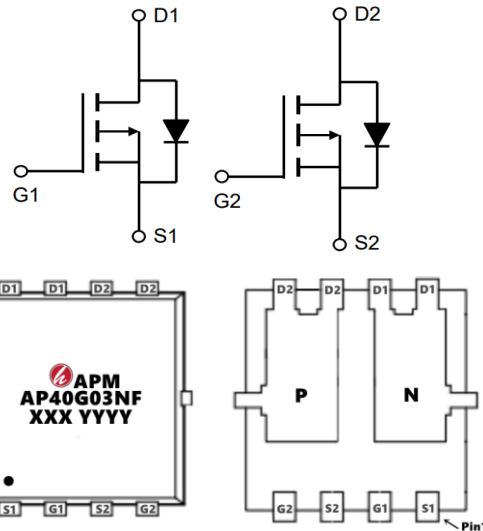
$R_{DS(ON)} < 13m\Omega$ @ $V_{GS}=-10V$ (Type: **9.0m Ω**)

Application

Wireless charging

Boost driver

Brushless motor



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP40G03NF	PDFN5*6-8L	AP40G03NF XXX YYYY	5000

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	N-Ch	P-Ch	Units
V_{DS}	Drain-Source Voltage	30	-30	V
V_{GS}	Gate-Source Voltage	± 20	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	42	-38	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	32.5	-27.5	A
I_{DM}	Pulsed Drain Current ²	123	-115	A
EAS	Single Pulse Avalanche Energy ³	289	378	mJ
I_{AS}	Avalanche Current	42	50	A
$P_D@T_C=25^\circ C$	Total Power Dissipation ⁴	46	41.3	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	25		$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.3		$^\circ C/W$

30V N+P-Channel Enhancement Mode MOSFET

N-Electrical Characteristics (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30	---	---	V
ΔBVDSS/ΔTJ	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.027	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =12A	---	6.5	10	mΩ
		V _{GS} =4.5V, I _D =10A	---	10	13	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	---	2.5	V
ΔVGS(th)	V _{GS(th)} Temperature Coefficient		---	-5.8	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =24V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V, I _D =15A	---	9.8	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =20V, V _{GS} =4.5V, I _D =12A	---	12.8	---	nC
Q _{gs}	Gate-Source Charge		---	3.3	---	
Q _{gd}	Gate-Drain Charge		---	6.5	---	
Td(on)	Turn-On Delay Time	V _{DD} =12V, V _{GS} =10V, R _G =3.3Ω I _D =5A	---	4.5	---	ns
T _r	Rise Time		---	10.8	---	
Td(off)	Turn-Off Delay Time		---	25.5	---	
T _f	Fall Time		---	9.6	---	
Ciss	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	1317	---	pF
Coss	Output Capacitance		---	163	---	
Crss	Reverse Transfer Capacitance		---	131	---	
IS	Continuous Source Current ^{1,6}	V _G =V _D =0V, Force Current	---	---	46	A
ISM	Pulsed Source Current ^{2,6}		---	---	92	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、 The power dissipation is limited by 175°C junction temperature
- 4、 EAS condition: T_J=25°C, V_{DD}= 24V, V_G= 10V, R_G=25Ω, L=0.1mH, I_{AS}= 34A
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

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P-Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250uA	-30	-34	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =-1mA	---	-0.0232	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-30A	---	9.0	13	mΩ
		V _{GS} =-4.5V, I _D =-15A	---	16	20	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.2	-1.4	-2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	4.6	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-24V, V _{GS} =0V, T _J =55°C	---	---	-5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =-5V, I _D =-30A	---	30	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	9	---	Ω
Q _g	Total Gate Charge (-4.5V)	V _{DS} =-15V, V _{GS} =-4.5V, I _D =-15A	---	22	---	nC
Q _{gs}	Gate-Source Charge		---	8.7	---	
Q _{gd}	Gate-Drain Charge		---	7.2	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =-15V, V _{GS} =-10V, R _G =3.3Ω, I _D =-15A	---	8	---	ns
T _r	Rise Time		---	73.7	---	
T _{d(off)}	Turn-Off Delay Time		---	61.8	---	
T _f	Fall Time		---	24.4	---	
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	2215	---	pF
C _{oss}	Output Capacitance		---	310	---	
C _{rss}	Reverse Transfer Capacitance		---	237	---	
I _s	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	-42	A
I _{SM}	Pulsed Source Current		---	---	-130	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-1A, T _J =25°C	---	---	-1	V
t _{rr}	Reverse Recovery Time	I _F =-15A, dI/dt=100A/μs, T _J =25°C	---	19	---	nS
Q _{rr}	Reverse Recovery Charge		---	9	---	nC

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、 The power dissipation is limited by 175°C junction temperature
- 4、 EAS condition: T_J=25°C, V_{DD}= -24V, V_G= -10V, R_G=7Ω, L=0.1mH, I_{AS}= -50A
- 5、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Typical Characteristics

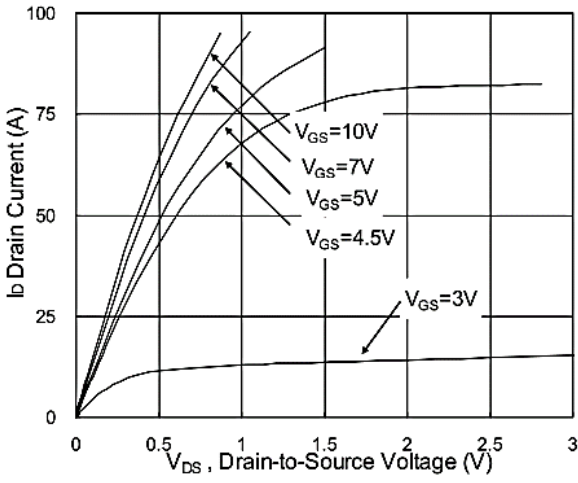


Fig.1 Typical Output Characteristics

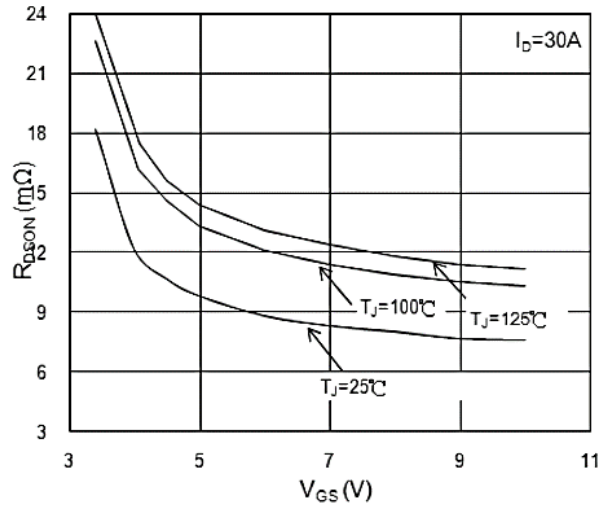


Fig.2 On-Resistance vs. Gate-Source

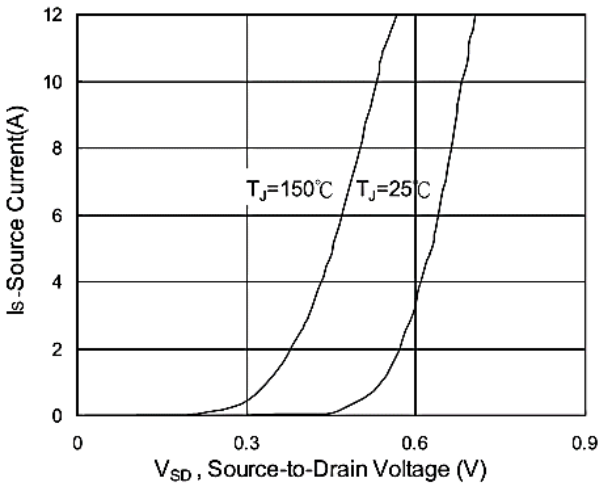


Fig.3 Forward Characteristics of reverse

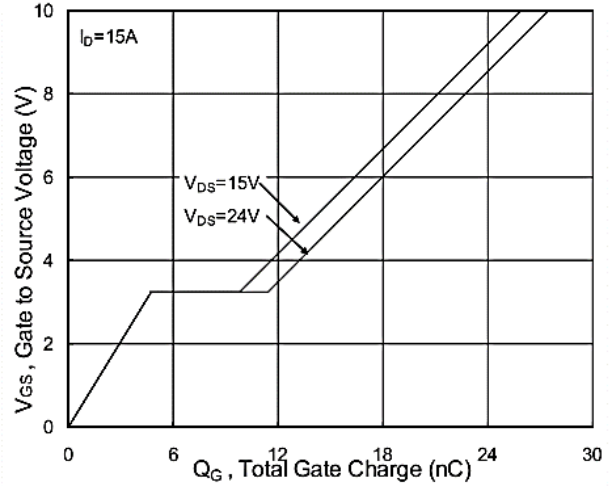


Fig.4 Gate-Charge Characteristics

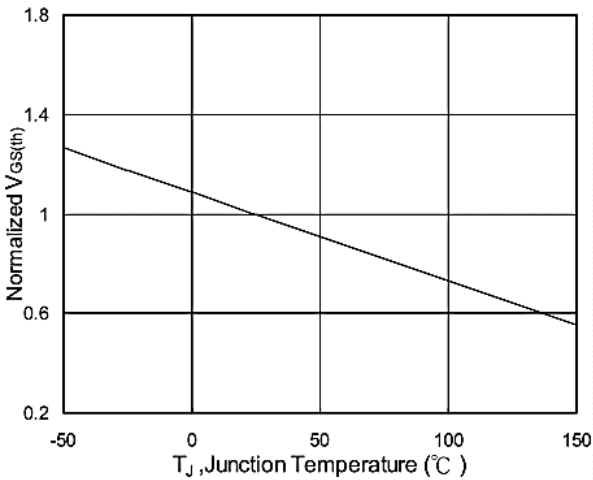


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

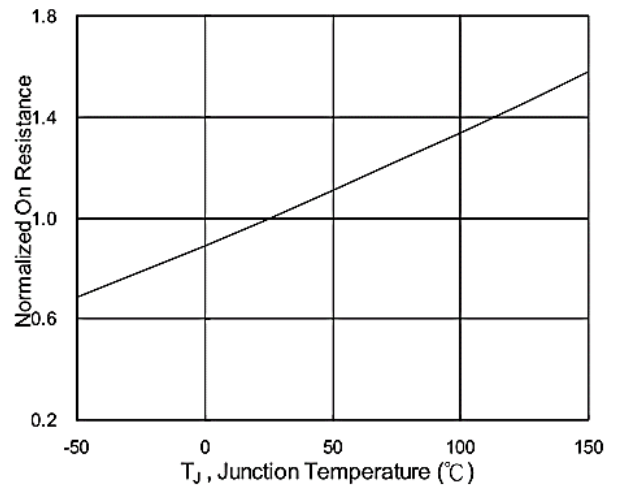


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

30V N+P-Channel Enhancement Mode MOSFET

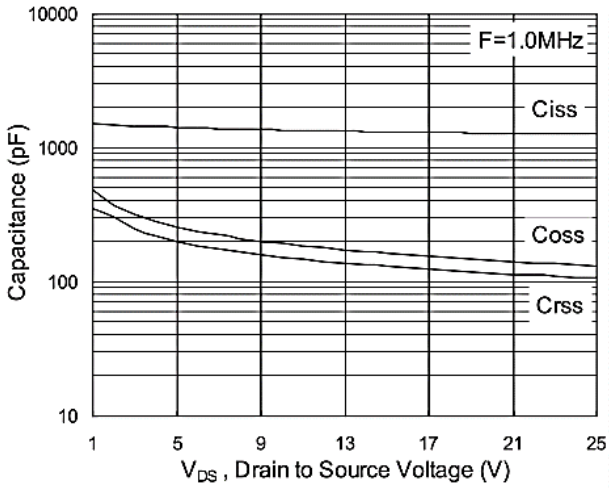


Fig.7 Capacitance

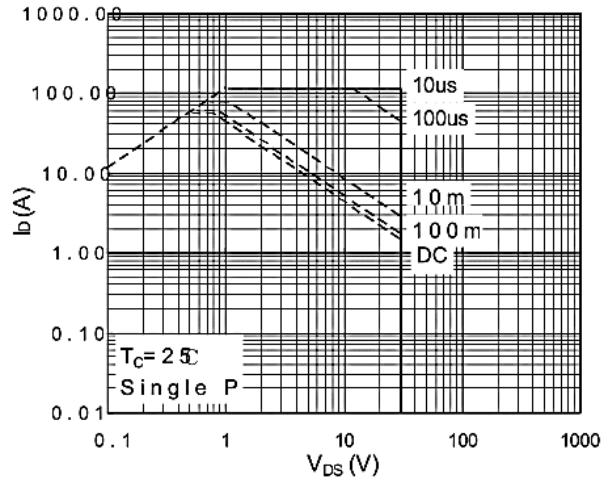


Fig.8 Safe Operating Area

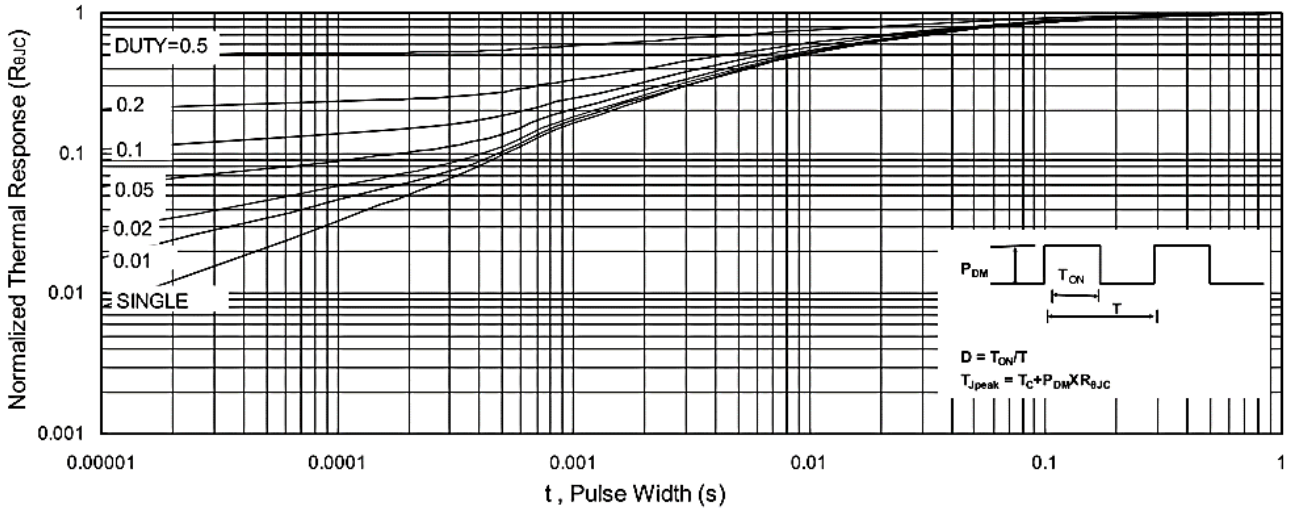


Fig.9 Normalized Maximum Transient Thermal Impedance

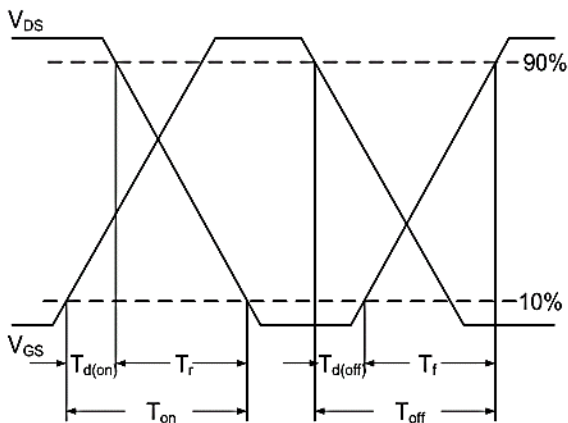


Fig.10 Switching Time Waveform

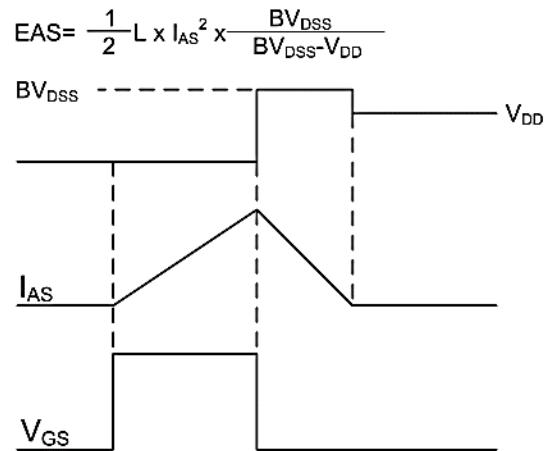


Fig.17 Unclamped Inductive Switching Waveform

P-Typical Characteristics

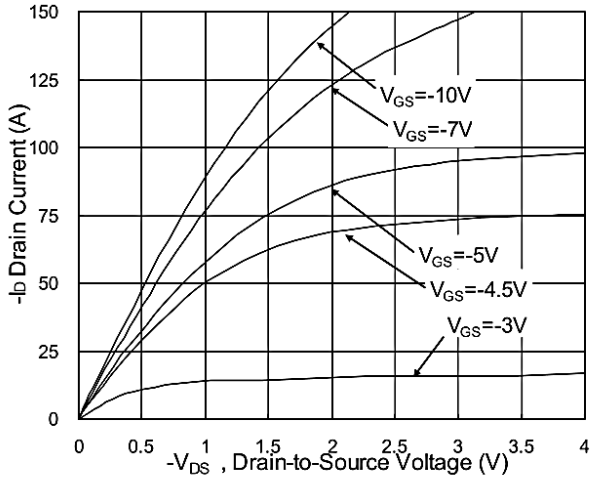


Fig.1 Typical Output Characteristics

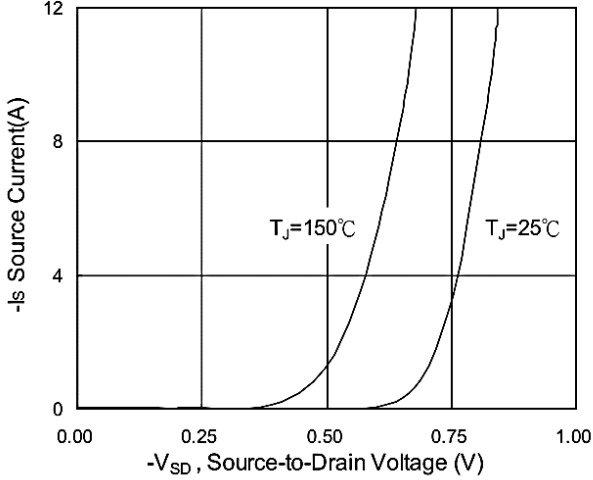


Fig.3 Forward Characteristics of Reverse

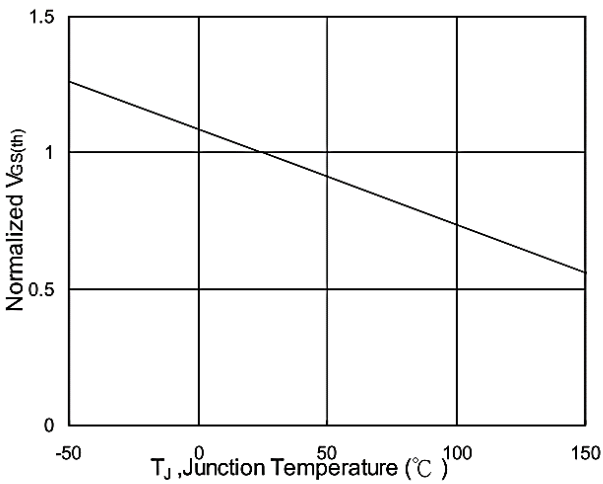


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

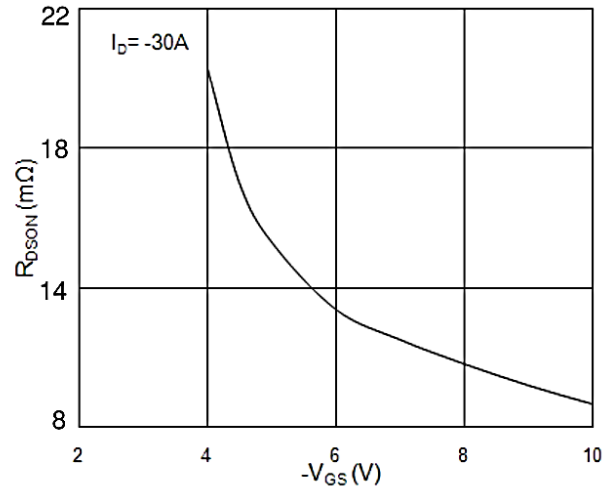


Fig.2 On-Resistance vs. G-S Voltage

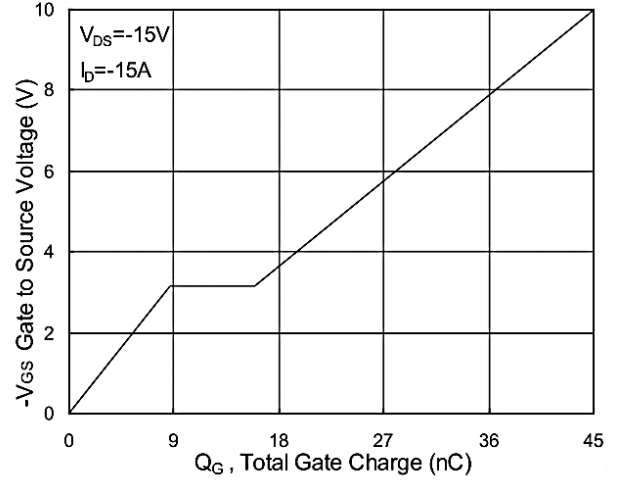


Fig.4 Gate-Charge Characteristics

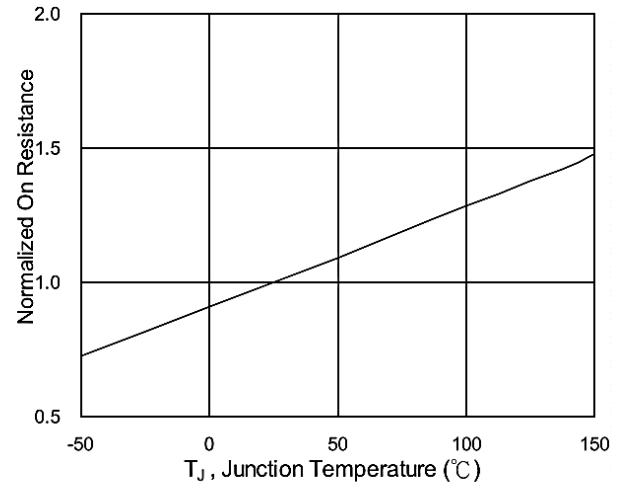


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

30V N+P-Channel Enhancement Mode MOSFET

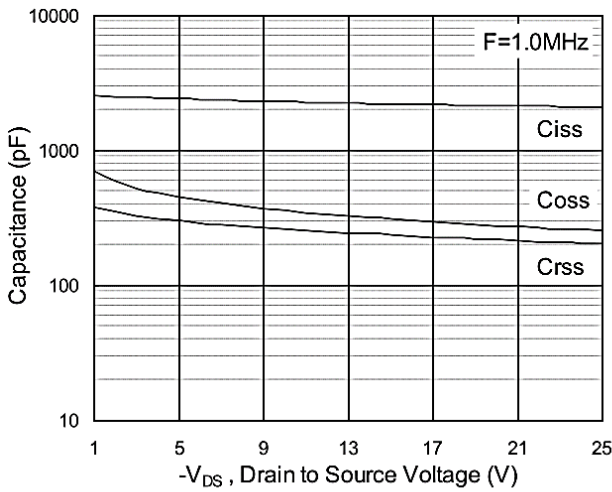


Fig.7 Capacitance

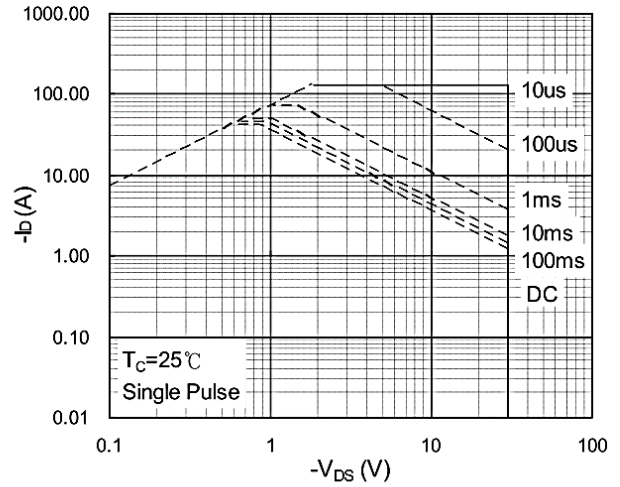


Fig.8 Safe Operating Area

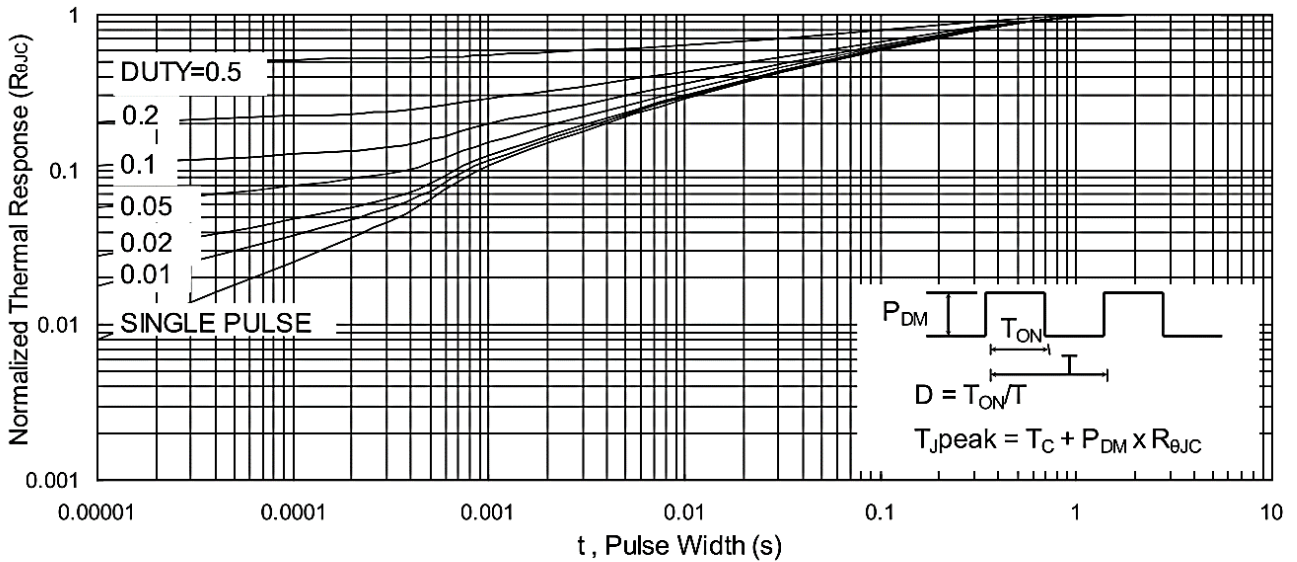


Fig.9 Normalized Maximum Transient Thermal Impedance

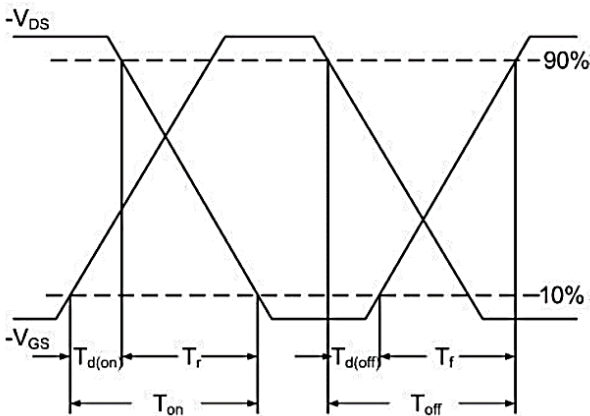


Fig.10 Switching Time Waveform

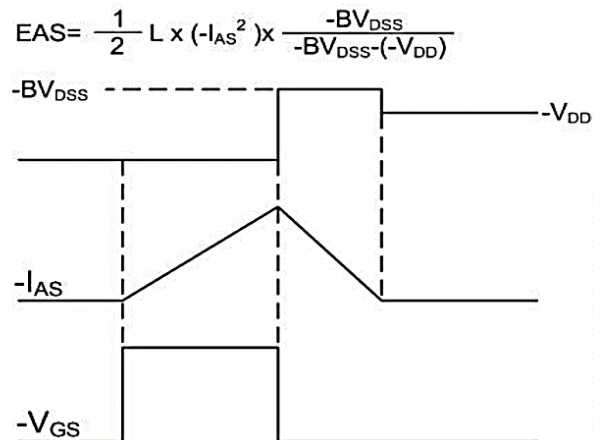
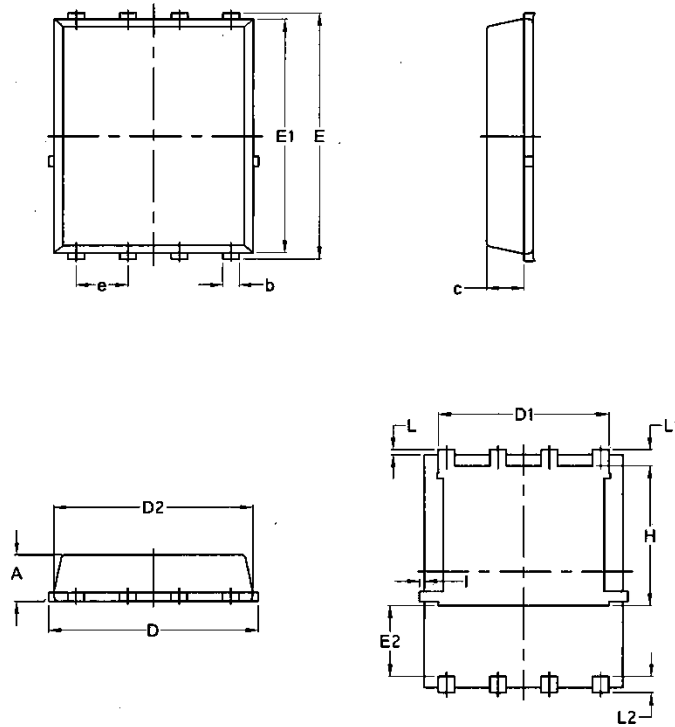


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-PDFN5*6-8L-JQ



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

30V N+P-Channel Enhancement Mode MOSFET**Attention**

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30V N+P-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2021/4/30	Initial release

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